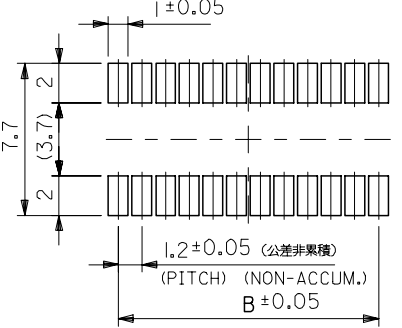
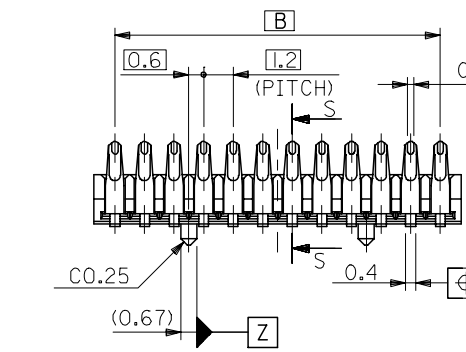


参考基板レイアウト
P.C.BOARD PATTERN DIM. (REF.)

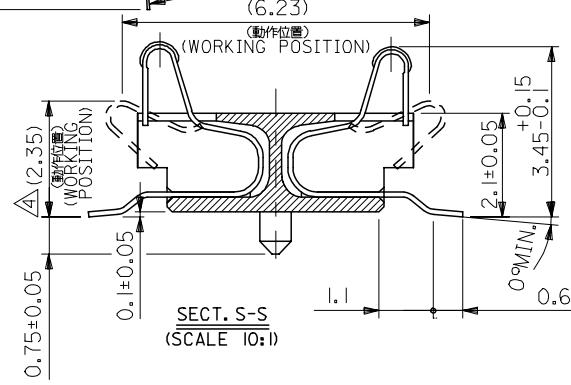


参考嵌合基板レイアウト
MATING P.C.BOARD PATTERN DIM. (REF.)

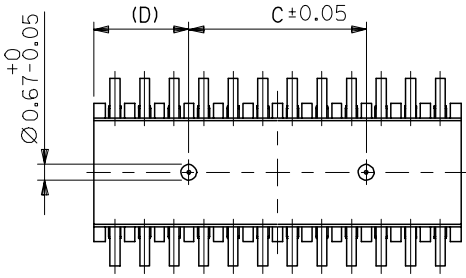


注記 NOTES

- 材質 MATERIAL
ハウジング : 液晶ポリマー (黒) UL94V-0
HOUSING : LIQUID CRYSTAL POLYMER [LCP], (BLACK), UL94V-0
ターミナル : 燐青銅 (t=0.1)
TERMINAL : PHOSPHOR BRONZE
- メッキ仕様 PLATING
接点部 : 金メッキ
CONTACT AREA : GOLD PLATING 0.4 MICROMETER MINIMUM
半田付け部 : 錫メッキ
SOLDER TAIL AREA : TIN PLATING 1.0 MICROMETER MINIMUM
下地メッキ : ニッケルメッキ
UNDER PLATING : NICKEL PLATING 2.0 MICROMETER MINIMUM
- コネクタを水平面上に置いた状態で維持する事。
TOLERANCES TO BE APPLIED WHEN ON A HORIZONTAL PLANE.
- 動作位置 (ストローク量 1.1mm) での接触力 : 0.46±0.05N {47±5gf}
NORMAL FORCE AT WORKING POSITION (STROKE 1.1mm) : 0.46±0.05N {47±5gf}
- 本製品は 54546-**-11 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54546-**-11.



SECT. S-S
(SCALE 10:1)



3.85	16.8	22.8	24.5	54546-4019	40
3.85	14.4	20.4	22.1	-3619	36
3.85	13.2	19.2	20.9	-3419	34
3.85	12	18	19.7	-3219	32
1.45	6	7.2	8.9	54546-1419	14
D	C	B	A	MATERIAL NO.	極数 CIRCUIT

MODEL NO.	54546-**-19				
GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS
		MM ONLY		5:1	METRIC
10 UNDER	±0.1	DRAWN BY	DATE	TITLE	
10 OVER 30 UNDER	±0.25	Y. WADA	'04/05/06	1.2 PITCH DUAL ONE PIECE CONN. HOUSING ASS'Y -LEAD FREE-	
30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED	
ANGULAR	±3 °	M. SASAO	'04/05/06	SD-54546-027	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	DOCUMENT NO.	SHEET NO.
		M. SASAO	'04/05/06	SD-54546-027	1 OF 1
		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		SIZE			
		A 3			